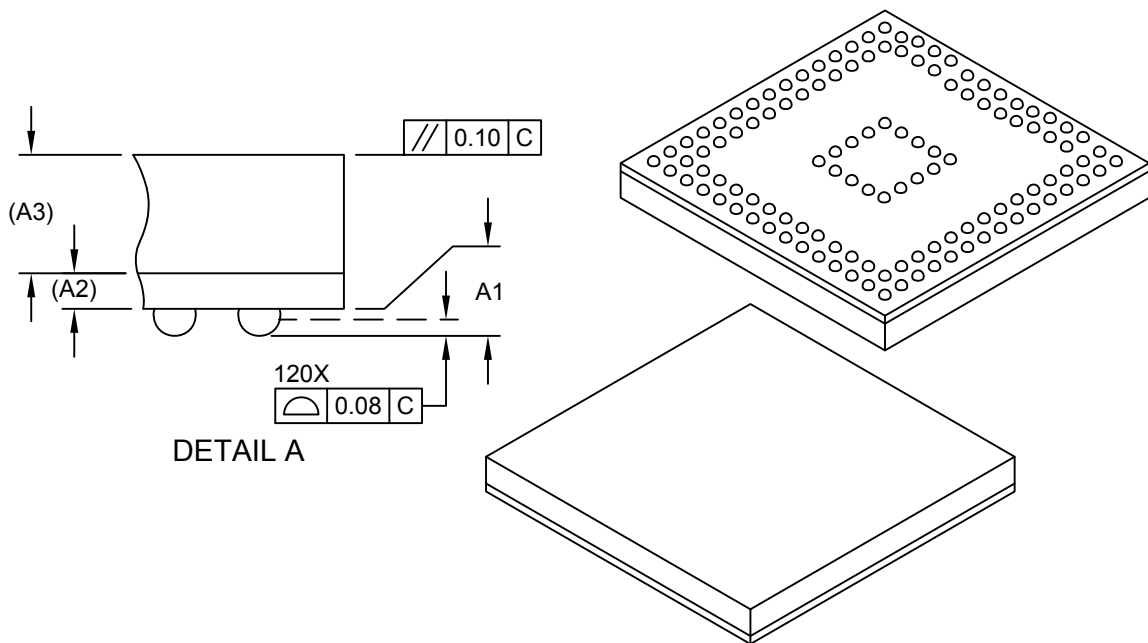


120-Ball Thin Fine Pitch Ball Grid Array Package (HEB) - 8x8 mm Body [TFBGA]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



		Units	MILLIMETERS		
Dimension Limits			MIN	NOM	MAX
Number of Terminals	N	120			
Pitch	e	0.50 BSC			
Overall Height	A	-	-	1.20	
Standoff	A1	0.11	-	0.21	
Substrate Thickness	A2	2.10 REF			
Mold Cap Thickness	A3	0.70 REF			
Overall Length	D	8.00 BSC			
Overall Ball Pitch	D1	7.00 BSC			
Overall Width	E	8.00 BSC			
Exposed Pad Width	E1	7.00 BSC			
Terminal Width	b	0.20	-	0.30	

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.
2. Package is saw singulated
3. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

REF: Reference Dimension, usually without tolerance, for information purposes only.